

Micropower Voltage Reference Diodes

LM285, LM385B

The LM285/LM385 series are micropower two-terminal bandgap voltage regulator diodes. Designed to operate over a wide current range of 10 μA to 20 mA, these devices feature exceptionally low dynamic impedance, low noise and stable operation over time and temperature. Tight voltage tolerances are achieved by on-chip trimming. The large dynamic operating range enables these devices to be used in applications with widely varying supplies with excellent regulation. Extremely low operating current make these devices ideal for micropower circuitry like portable instrumentation, regulators and other analog circuitry where extended battery life is required.

The LM285/LM385 series are packaged in a low cost TO-226 plastic case and are available in two voltage versions of 1.235 V and 2.500 V as denoted by the device suffix (see Ordering Information table). The LM285 is specified over a -40° C to $+85^{\circ}$ C temperature range while the LM385 is rated from 0° C to $+70^{\circ}$ C.

The LM385 is also available in a surface mount plastic package in voltages of 1.235 V and 2.500 V.

Features

- Operating Current from 10 μA to 20 mA
- 1.0%, 1.5%, 2.0% and 3.0% Initial Tolerance Grades
- Low Temperature Coefficient
- 1.0 Ω Dynamic Impedance
- Surface Mount Package Available
- These Devices are Pb-Free and are RoHS Compliant

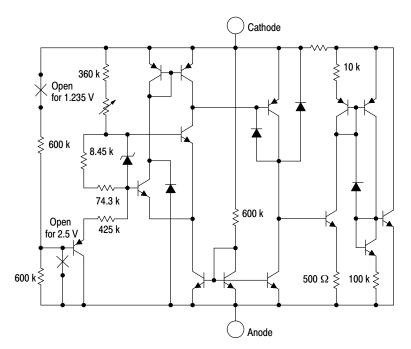


Figure 1. Representative Schematic Diagram

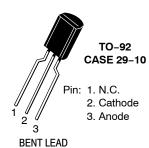
MARKING DIAGRAMS



SOIC-8 D SUFFIX CASE 751





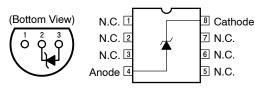


xxx = 1.2 or 2.5 y = 2 or 3 z = 1 or 2

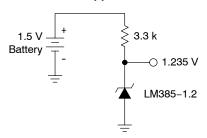
A = Assembly Location

L = Wafer Lot Y = Year W = Work Week ■ Pb-Free Package

(Note: Microdot may be in either location)



Standard Application



ORDERING INFORMATION

See detailed ordering and shipping information on page 6 of this data sheet.

MAXIMUM RATINGS ($T_A = 25^{\circ}C$, unless otherwise noted)

Rating	Symbol	Value	Unit
Reverse Current	I _R	30	mA
Forward Current	I _F	10	mA
Operating Ambient Temperature Range LM2 LM3		-40 to +85 0 to +70	°C
Operating Junction Temperature	TJ	+150	°C
Storage Temperature Range	T _{stg}	-65 to + 150	°C
Electrostatic Discharge Sensitivity (ESD) Human Body Model (HBM) Machine Model (MM) Charged Device Model (CDM)	ESD	4000 400 2000	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

ELECTRICAL CHARACTERISTICS (T_A = 25°C, unless otherwise noted)

		L	M285-1.2	2	LM385-1.2/LM385B-1.2			
Characteristic	Symbol	Min	Тур	Max	Min	Тур	Max	Unit
$\label{eq:Reverse Breakdown Voltage (I_{Rmin} \le I_R \le 20 \text{ mA})} \\ LM285-1.2/LM385B-1.2 \\ T_A = T_{low} \text{ to } T_{high} \text{ (Note 1)} \\ LM385-1.2 \\ T_A = T_{low} \text{ to } T_{high} \text{ (Note 1)} \\$	V _{(BR)R}	1.223 1.200 - -	1.235 - - -	1.247 1.270 - -	1.223 1.210 1.205 1.192	1.235 - 1.235 -	1.247 1.260 1.260 1.273	V
Minimum Operating Current $T_A = 25^{\circ}C$ $T_A = T_{low}$ to T_{high} (Note 1)	I _{Rmin}	- -	8.0 -	10 20	-	8.0 -	15 20	μΑ
Reverse Breakdown Voltage Change with Current $I_{Rmin} \leq I_R \leq 1.0$ mA, $T_A = +25^{\circ}C$ $T_A = T_{low}$ to T_{high} (Note 1) 1.0 mA $\leq I_R \leq 20$ mA, $T_A = +25^{\circ}C$ $T_A = T_{low}$ to T_{high} (Note 1)	$\Delta V_{(BR)R}$	- - - -	- - -	1.0 1.5 10 20	- - - -	- - - -	1.0 1.5 20 25	mV
Reverse Dynamic Impedance $I_R = 100 \mu A, T_A = +25 ^{\circ} C$	Z	-	0.6	_	-	0.6	_	Ω
Average Temperature Coefficient 10 μ A \leq I _R \leq 20 mA, T _A = T _{low} to T _{high} (Note 1)	$\Delta V_{(BR)}/\Delta T$	-	80	-	-	80	-	ppm/°C
Wideband Noise (RMS) $I_R = 100 \mu A$, $10 \ Hz \le f \le 10 \ kHz$	n	-	60	-	_	60	-	μV
Long Term Stability $I_R = 100 \ \mu A, \ T_A = +25^{\circ}C \pm 0.1^{\circ}C$	S	-	20	-	-	20	-	ppm/kHR
$\label{eq:Reverse Breakdown Voltage (I_{Rmin} \le I_R \le 20 \text{ mA})} \\ LM285-2.5/LM385B-2.5 \\ T_A = T_{low} \text{ to } T_{high} \text{ (Note 1)} \\ LM385-2.5 \\ T_A = T_{low} \text{ to } T_{high} \text{ (Note 1)} \\$	V _{(BR)R}	2.462 2.415 - -	2.5 - - -	2.538 2.585 - -	2.462 2.436 2.425 2.400	2.5 - 2.5 -	2.538 2.564 2.575 2.600	V
Minimum Operating Current $T_{A} = 25^{\circ}C$ $T_{A} = T_{low} \text{ to } T_{high} \text{ (Note 1)}$	I _{Rmin}	-	13 -	20 30	-	13 -	20 30	μА

 $[\]begin{array}{ll} T_{low} & = -40^{\circ}\text{C for LM285} - 1.2, \, \text{LM285} - 2.5 \\ T_{high} & = +85^{\circ}\text{C for LM285} - 1.2, \, \text{LM285} - 2.5 \\ T_{low} & = 0^{\circ}\text{C for LM385} - 1.2, \, \text{LM385B} - 1.2, \, \text{LM385} - 2.5, \, \text{LM385B} - 2.5 \\ T_{high} & = +70^{\circ}\text{C for LM385} - 1.2, \, \text{LM385B} - 1.2, \, \text{LM385} - 2.5, \, \text{LM385B} - 2.5 \end{array}$

ELECTRICAL CHARACTERISTICS ($T_A = 25$ °C, unless otherwise noted)

		L	M285-1.2	2	LM385-	-1.2/LM38	5B-1.2	
Characteristic	Symbol	Min	Тур	Max	Min	Тур	Max	Unit
$\label{eq:Reverse Breakdown Voltage Change with Current} \begin{split} & I_{Rmin} \leq I_R \leq 1.0 \text{ mA}, T_A = +25^{\circ}\text{C} \\ & T_A = T_{low} \text{ to } T_{high} \text{ (Note 2)} \\ & 1.0 \text{ mA} \leq I_R \leq 20 \text{ mA}, T_A = +25^{\circ}\text{C} \\ & T_A = T_{low} \text{ to } T_{high} \text{ (Note 2)} \end{split}$	$\Delta V_{(BR)R}$	1111	1 1 1 1	1.0 1.5 10 20		1 1 1 1	2.0 2.5 20 25	mV
Reverse Dynamic Impedance $I_R = 100 \mu A, T_A = +25^{\circ}C$	Z	-	0.6	-	-	0.6	-	Ω
Average Temperature Coefficient 20 μ A \leq I _R \leq 20 mA, T _A = T _{low} to T _{high} (Note 2)	$\Delta V_{(BR)}/\Delta T$	1	80	1	-	80	ı	ppm/°C
Wideband Noise (RMS) $I_R = 100 \ \mu\text{A}, \ 10 \ \text{Hz} \le f \le 10 \ \text{kHz}$	n	- 1	120		-	120	- 1	μV
Long Term Stability $I_R = 100 \ \mu A, T_A = +25^{\circ}C \pm 0.1^{\circ}C$	S	-	20	-	_	20	-	ppm/kHR

^{2.} $T_{low} = -40^{\circ}\text{C}$ for LM285–1.2, LM285–2.5 $T_{high} = +85^{\circ}\text{C}$ for LM285–1.2, LM285–2.5 $T_{low} = 0^{\circ}\text{C}$ for LM385–1.2, LM385B–1.2, LM385–2.5, LM385B–2.5 $T_{high} = +70^{\circ}\text{C}$ for LM385–1.2, LM385B–1.2, LM385–2.5, LM385B–2.5

TYPICAL PERFORMANCE CURVES FOR LM285-1.2/385-1.2/385B-1.2

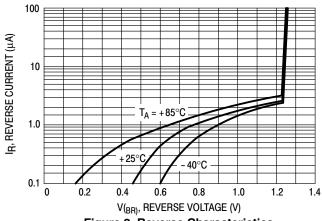


Figure 2. Reverse Characteristics

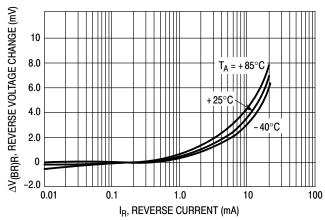


Figure 3. Reverse Characteristics

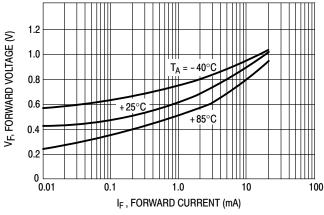


Figure 4. Forward Characteristics

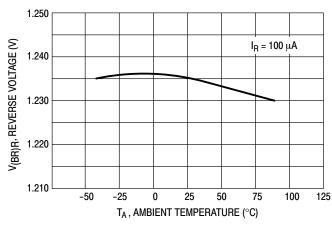


Figure 5. Temperature Drift

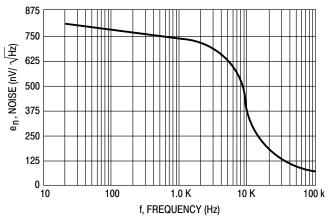


Figure 6. Noise Voltage

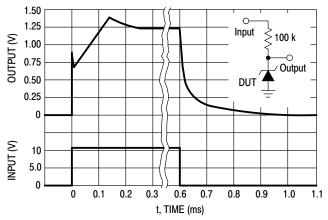


Figure 7. Response Time

TYPICAL PERFORMANCE CURVES FOR LM285-2.5/385-2.5/385B-2.5

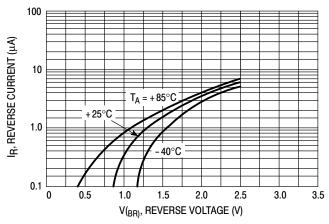
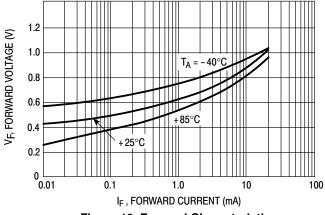


Figure 8. Reverse Characteristics

Figure 9. Reverse Characteristics



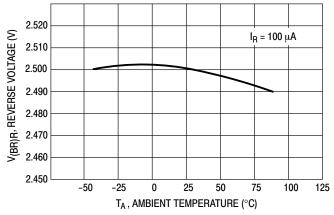
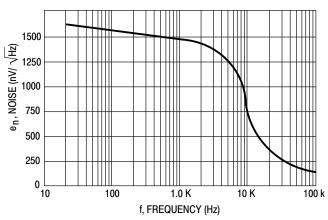


Figure 10. Forward Characteristics

Figure 11. Temperature Drift



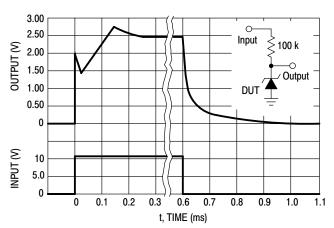


Figure 12. Noise Voltage

Figure 13. Response Time

ORDERING INFORMATION

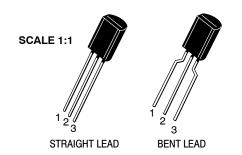
Device	Operating Temperature Range	Reverse Break-Down Voltage	Package	Shipping [†]
LM285D-1.2			SOIC-8	98 Units / Rail
LM285D-1.2G]		SOIC-8 (Pb-Free)	98 Units / Rail
LM285D-1.2R2		1.235 V	SOIC-8	2500 / Tape & Reel
LM285D-1.2R2G]		SOIC-8 (Pb-Free)	2500 / Tape & Reel
LM285D-2.5			SOIC-8	98 Units / Rail
LM285D-2.5G		2.500.V	SOIC-8 (Pb-Free)	98 Units / Rail
LM285D-2.5R2		2.500 V	SOIC-8	2500 / Tape & Reel
LM285D-2.5R2G			SOIC-8 (Pb-Free)	2500 / Tape & Reel
LM285Z-1.2			TO-92	2000 Units / Bag
LM285Z-1.2G	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	1.235 V	TO-92 (Pb-Free)	2000 Units / Bag
LM285Z-2.5			TO-92	2000 Units / Bag
LM285Z-2.5G		2.500 V	TO-92 (Pb-Free)	2000 Units / Bag
LM285Z-1.2RA			TO-92	2000 / Tape & Reel
LM285Z-1.2RAG		1.235 V	TO-92 (Pb-Free)	2000 / Tape & Reel
LM285Z-2.5RA		2.500 V	TO-92	2000 / Tape & Reel
LM285Z-2.5RAG			TO-92 (Pb-Free)	2000 / Tape & Reel
LM285Z-2.5RP			TO-92	2000 Units / Fan-Fold
LM285Z-2.5RPG			TO-92 (Pb-Free)	2000 Units / Fan-Fold
LM385BD-1.2			SOIC-8	98 Units / Rail
LM385BD-1.2G		1.235 V	SOIC-8 (Pb-Free)	98 Units / Rail
LM385BD-1.2R2		1.203 V	SOIC-8	2500 / Tape & Reel
LM385BD-1.2R2G			SOIC-8 (Pb-Free)	2500 / Tape & Reel
LM385BD-2.5			SOIC-8	98 Units / Rail
LM385BD-2.5G	T _A = 0°C to +70°C	2.500 V	SOIC-8 (Pb-Free)	98 Units / Rail
LM385BD-2.5R2	IA = 0 0 10 +/0-0	2.300 V	SOIC-8	2500 / Tape & Reel
LM385BD-2.5R2G			SOIC-8 (Pb-Free)	2500 / Tape & Reel
LM385BZ-1.2			TO-92	2000 Units / Bag
LM385BZ-1.2G		1 235 \/	TO-92 (Pb-Free)	2000 Units / Bag
LM385BZ-1.2RA		1.235 V	TO-92	2000 / Tape & Reel
LM385BZ-1.2RAG			TO-92 (Pb-Free)	2000 / Tape & Reel
	•			

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ORDERING INFORMATION

Device	Operating Temperature Range	Reverse Break-Down Voltage	Package	Shipping [†]
LM385BZ-2.5			TO-92	2000 Units / Bag
LM385BZ-2.5G]		TO-92 (Pb-Free)	2000 Units / Bag
_M385BZ-2.5RA		2.500 V	TO-92	2000 / Tape & Reel
LM385BZ-2.5RAG]		TO-92 (Pb-Free)	2000 / Tape & Reel
LM385D-1.2			SOIC-8	98 Units / Rail
LM385D-1.2G]	1 005 \	SOIC-8 (Pb-Free)	98 Units / Rail
LM385D-1.2R2		1.235 V	SOIC-8	2500 / Tape & Reel
LM385D-1.2R2G			SOIC-8 (Pb-Free)	2500 / Tape & Reel
LM385D-2.5			SOIC-8	98 Units / Rail
_M385D-2.5G		0.500.4	SOIC-8 (Pb-Free)	98 Units / Rail
_M385D-2.5R2		2.500 V	SOIC-8	2500 / Tape & Reel
LM385D-2.5R2G	$T_A = 0$ °C to +70°C		SOIC-8 (Pb-Free)	2500 / Tape & Reel
_M385Z-1.2			TO-92	2000 Units / Bag
LM385Z-1.2G			TO-92 (Pb-Free)	2000 Units / Bag
_M385Z-1.2RA			TO-92	2000 / Tape & Reel
_M385Z-1.2RAG]	1.235 V	TO-92 (Pb-Free)	2000 / Tape & Reel
_M385Z-1.2RP			TO-92	2000 / Ammo Box
_M385Z-1.2RPG			TO-92 (Pb-Free)	2000 / Ammo Box
_M385Z-2.5			TO-92	2000 Units / Bag
_M385Z-2.5G		0.500.V	TO-92 (Pb-Free)	2000 Units / Bag
_M385Z-2.5RP		2.500 V	TO-92	2000 / Ammo Box
LM385Z-2.5RPG			TO-92 (Pb-Free)	2000 / Ammo Box

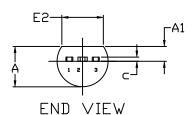
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

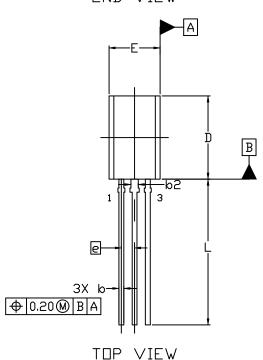


TO-92 (TO-226) 1 WATT CASE 29-10 ISSUE D

DATE 05 MAR 2021

STRAIGHT LEAD





NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR GATE PROTRUSIONS.
- 4. DIMENSION 6 AND 62 DOES NOT INCLUDE DAMBAR PROTRUSION. LEAD WIDTH INCLUDING PROTRUSION SHALL NOT EXCEED 0.20. DIMENSION 62 LOCATED ABOVE THE DAMBAR PORTION OF MIDDLE LEAD.

	MILLIMETERS				
DIM	MIN.	N□M.	MAX.		
Α	3.75	3.90	4.05		
A1	1.28	1.43	1.58		
b	0.38	0.465	0.55		
b2	0.62	0.70	0.78		
c	0.35	0.40	0.45		
D	7.85	8.00	8.15		
E	4.75	4.90	5.05		
E2	3.90				
е	1.27 BSC				
L	13.80	14.00	14.20		

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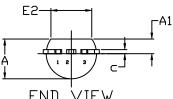
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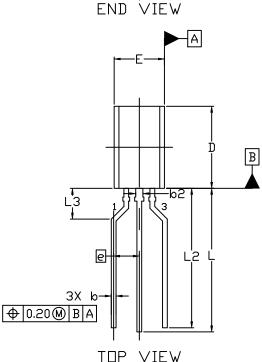


TO-92 (TO-226) 1 WATT CASE 29-10 ISSUE D

DATE 05 MAR 2021

FORMED LEAD





NOTES:

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- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR GATE PROTRUSIONS.
- 4. DIMENSION 6 AND 62 DOES NOT INCLUDE DAMBAR PROTRUSION. LEAD WIDTH INCLUDING PROTRUSION SHALL NOT EXCEED 0.20. DIMENSION 62 LOCATED ABOVE THE DAMBAR PORTION OF MIDDLE LEAD.

	MILLIMETERS					
DIM	MIN.	N□M.	MAX.			
Α	3.75	3.90	4.05			
A1	1.28	1.43	1.58			
b	0.38	0.465	0.55			
b2	0.62	0.70	0.78			
С	0.35	0.40	0.45			
D	7.85	8.00	8.15			
Е	4.75	4.90	5.05			
E2	3.90					
е	2.50 BSC					
L	13.80	14.00	14.20			
L2	13.20	13.60	14.00			
L3	3.00 REF					

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TO-92 (TO-226) 1 WATT

CASE 29-10 ISSUE D

DATE 05 MAR 2021

STYLE 1: PIN 1. 2. 3.	EMITTER BASE COLLECTOR	STYLE 2: PIN 1. 2. 3.	BASE EMITTER COLLECTOR	STYLE 3: PIN 1. 2. 3.	ANODE ANODE CATHODE	PIN 1. 2.	CATHODE CATHODE ANODE	STYLE 5: PIN 1. 2. 3.	DRAIN SOURCE GATE
	CATE	DIM 4		2.	DRAIN	PIN 1. 2.		2.	CATHODE GATE ANODE
2.	CATHODE & ANODE	2.		2.	ANODE 1	2.	EMITTER		
2.	ANODE	PIN 1	COLLECTOR BASE EMITTER	PIN 1	ANODE	2.	GATE ANODE CATHODE	2.	NOT CONNECTED CATHODE ANODE
2.			GATE	PIN 1. 2.		PIN 1. 2.	EMITTER COLLECTOR/ANODE CATHODE	PIN 1. 2.	
	V _{CC}	2.	MT	2.	CATHODE	PIN 1. 2.	NOT CONNECTED ANODE CATHODE	PIN 1. 2.	DRAIN GATE SOURCE
		STYLE 32: PIN 1. 2. 3.	BASE COLLECTOR EMITTER	STYLE 33: PIN 1. 2. 3.	RETURN	PIN 1. 2.	INPUT GROUND LOGIC		

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code

A = Assembly Location

L = Wafer Lot Y = Year

W = Work Week

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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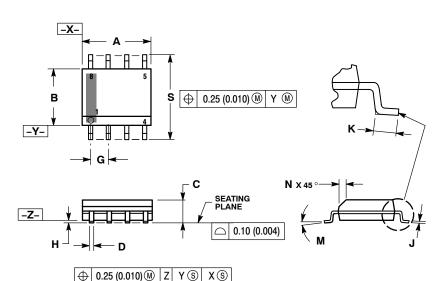
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SOIC-8 NB CASE 751-07 **ISSUE AK**

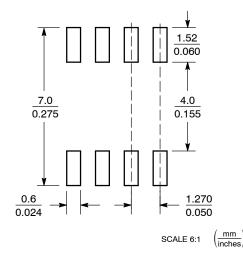
DATE 16 FEB 2011



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
- ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE
- DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
- 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

	MILLIMETERS		RS INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	4.80	5.00	0.189	0.197	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.053	0.069	
D	0.33	0.51	0.013	0.020	
G	1.27	7 BSC	0.050 BSC		
Н	0.10	0.25	0.004	0.010	
J	0.19	0.25	0.007	0.010	
K	0.40	1.27	0.016	0.050	
М	0 °	8 °	0 °	8 °	
N	0.25	0.50	0.010	0.020	
S	5.80	6.20	0.228	0.244	

SOLDERING FOOTPRINT*



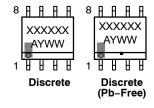
^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code = Assembly Location = Wafer Lot = Year = Work Week

= Pb-Free Package



XXXXXX = Specific Device Code = Assembly Location Α

= Year ww = Work Week = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

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DATE 16 FEB 2011

			D, 11 2 10 1 2 D 2
STYLE 1: PIN 1. EMITTER 2. COLLECTOR 3. COLLECTOR 4. EMITTER 5. EMITTER 6. BASE 7. BASE 8. EMITTER	STYLE 2: PIN 1. COLLECTOR, DIE, #1 2. COLLECTOR, #1 3. COLLECTOR, #2 4. COLLECTOR, #2 5. BASE, #2 6. EMITTER, #2 7. BASE, #1 8. EMITTER, #1	STYLE 3: PIN 1. DRAIN, DIE #1 2. DRAIN, #1 3. DRAIN, #2 4. DRAIN, #2 5. GATE, #2 6. SOURCE, #2 7. GATE, #1 8. SOURCE, #1	STYLE 4: PIN 1. ANODE 2. ANODE 3. ANODE 4. ANODE 5. ANODE 6. ANODE 7. ANODE 8. COMMON CATHODE
STYLE 5: PIN 1. DRAIN 2. DRAIN 3. DRAIN 4. DRAIN 5. GATE 6. GATE 7. SOURCE 8. SOURCE	STYLE 6: PIN 1. SOURCE 2. DRAIN 3. DRAIN 4. SOURCE 5. SOURCE 6. GATE 7. GATE 8. SOURCE	STYLE 7: PIN 1. INPUT 2. EXTERNAL BYPASS 3. THIRD STAGE SOURCE 4. GROUND 5. DRAIN 6. GATE 3 7. SECOND STAGE Vd 8. FIRST STAGE Vd	STYLE 8: PIN 1. COLLECTOR, DIE #1 2. BASE, #1 3. BASE, #2 4. COLLECTOR, #2 5. COLLECTOR, #2 6. EMITTER, #2 7. EMITTER, #1 8. COLLECTOR, #1
STYLE 9: PIN 1. EMITTER, COMMON 2. COLLECTOR, DIE #1 3. COLLECTOR, DIE #2 4. EMITTER, COMMON 5. EMITTER, COMMON 6. BASE, DIE #2 7. BASE, DIE #1 8. EMITTER, COMMON	STYLE 10: PIN 1. GROUND 2. BIAS 1 3. OUTPUT 4. GROUND 5. GROUND 6. BIAS 2 7. INPUT 8. GROUND	STYLE 11: PIN 1. SOURCE 1 2. GATE 1 3. SOURCE 2 4. GATE 2 5. DRAIN 2 6. DRAIN 2 7. DRAIN 1 8. DRAIN 1	STYLE 12: PIN 1. SOURCE 2. SOURCE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN
STYLE 13: PIN 1. N.C. 2. SOURCE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN	STYLE 14: PIN 1. N-SOURCE 2. N-GATE 3. P-SOURCE 4. P-GATE 5. P-DRAIN 6. P-DRAIN 7. N-DRAIN 8. N-DRAIN	8. DRAIN 1 STYLE 15: PIN 1. ANODE 1 2. ANODE 1 3. ANODE 1 4. ANODE 1 5. CATHODE, COMMON 6. CATHODE, COMMON 7. CATHODE, COMMON 8. CATHODE, COMMON	STYLE 16: PIN 1. EMITTER, DIE #1 2. BASE, DIE #1 3. EMITTER, DIE #2 4. BASE, DIE #2 5. COLLECTOR, DIE #2 6. COLLECTOR, DIE #2 7. COLLECTOR, DIE #1 8. COLLECTOR, DIE #1
STYLE 17: PIN 1. VCC 2. V2OUT 3. V1OUT 4. TXE 5. RXE 6. VEE 7. GND 8. ACC STYLE 21: PIN 1. CATHODE 1 2. CATHODE 2 3. CATHODE 3 4. CATHODE 4 5. CATHODE 5	STYLE 18: PIN 1. ANODE 2. ANODE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. CATHODE 8. CATHODE STYLE 22: PIN 1. I/O LINE 1 2. COMMON CATHODE/VCC 3. COMMON CATHODE/VCC 4. I/O LINE 3 5. COMMON ANODE/GND	STYLE 19: PIN 1. SOURCE 1 2. GATE 1 3. SOURCE 2 4. GATE 2 5. DRAIN 2 6. MIRROR 2 7. DRAIN 1 8. MIRROR 1 STYLE 23: PIN 1. LINE 1 IN 2. COMMON ANODE/GND 3. COMMON ANODE/GND 4. LINE 2 IN 5. LINE 2 OUT	STYLE 20: PIN 1. SOURCE (N) 2. GATE (N) 3. SOURCE (P) 4. GATE (P) 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN STYLE 24: PIN 1. BASE 2. EMITTER 3. COLLECTOR/ANODE 4. COLLECTOR/ANODE 5. CATHODE
6. COMMON ANODE7. COMMON ANODE8. CATHODE 6 STYLE 25:	6. I/O LINE 4 7. I/O LINE 5 8. COMMON ANODE/GND STYLE 26: PIN 1. GND	6. COMMON ANODE/GND 7. COMMON ANODE/GND 8. LINE 1 OUT STYLE 27:	6. CATHODE 7. COLLECTOR/ANODE 8. COLLECTOR/ANODE STYLE 28:
PIN 1. VIN 2. N/C 3. REXT 4. GND 5. IOUT 6. IOUT 7. IOUT 8. IOUT STYLE 29:	2. dv/dt 2. dv/dt 3. ENABLE 4. ILIMIT 5. SOURCE 6. SOURCE 7. SOURCE 8. VCC STYLE 30:	PIN 1. ILIMIT 2. OVLO 3. UVLO 4. INPUT+ 5. SOURCE 6. SOURCE 7. SOURCE 8. DRAIN	PIN 1. SW_TO_GND 2. DASIC_OFF 3. DASIC_SW_DET 4. GND 5. V_MON 6. VBULK 7. VBULK 8. VIN
PIN 1. BASE, DIE #1 2. EMITTER, #1 3. BASE, #2 4. EMITTER, #2 5. COLLECTOR, #2 6. COLLECTOR, #2 7. COLLECTOR, #1 8. COLLECTOR, #1	PIN 1. DRAIN 1 2. DRAIN 1 3. GATE 2 4. SOURCE 2 5. SOURCE 1/DRAIN 2 6. SOURCE 1/DRAIN 2 7. SOURCE 1/DRAIN 2 8. GATE 1		

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